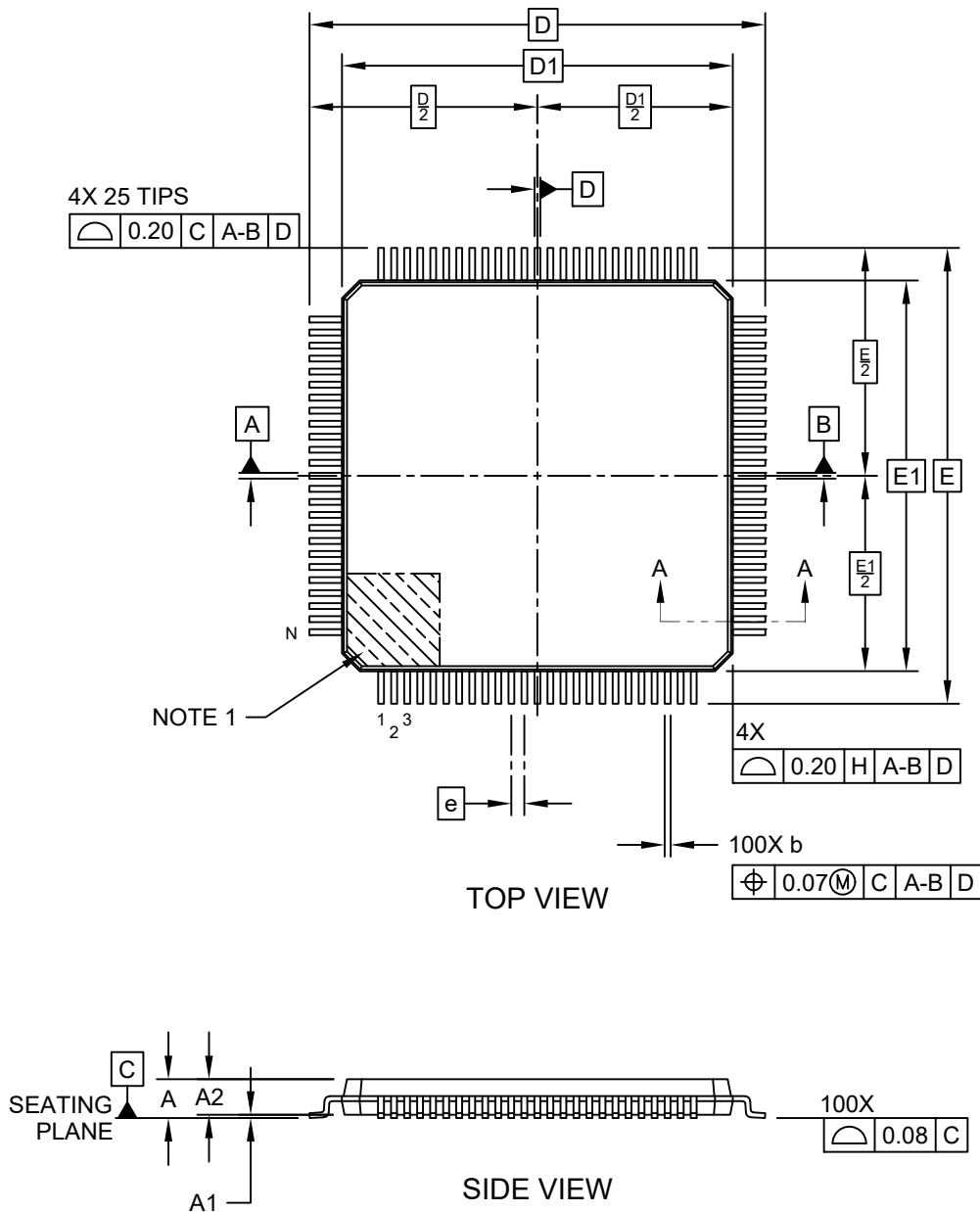


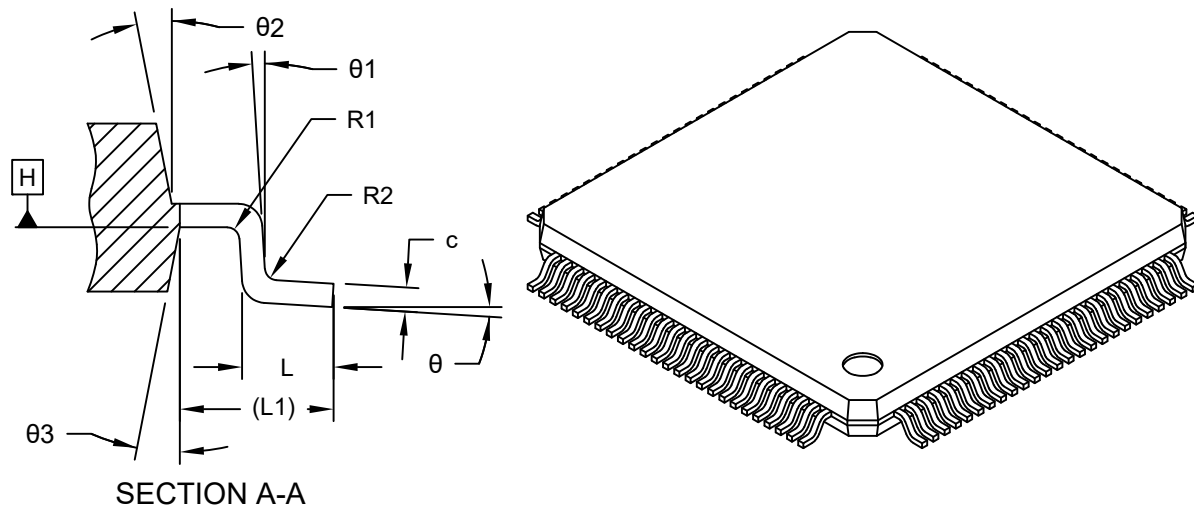
100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

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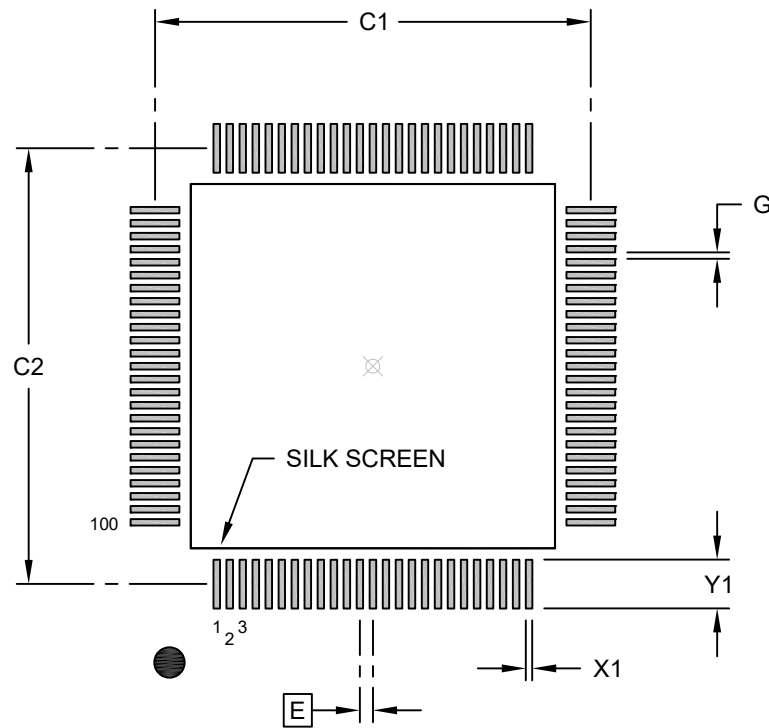
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Standoff	A1	0.05	–	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Length	D	14.00 BSC		
Molded Package Length	D1	12.00 BSC		
Overall Width	E	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Lead Width	b	0.13	0.18	0.23
Lead Thickness	c	0.09	–	0.20
Lead Bend Radius	R1	0.08	–	–
Lead Bend Radius	R2	0.08	–	0.20
Foot Angle	θ	0°	–	7°
Lead Angle	θ_1	0°	–	–
Mold Draft Angle	θ_2	11°	12°	13°
Mold Draft Angle	θ_3	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.

100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

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RECOMMENDED LAND PATTERN

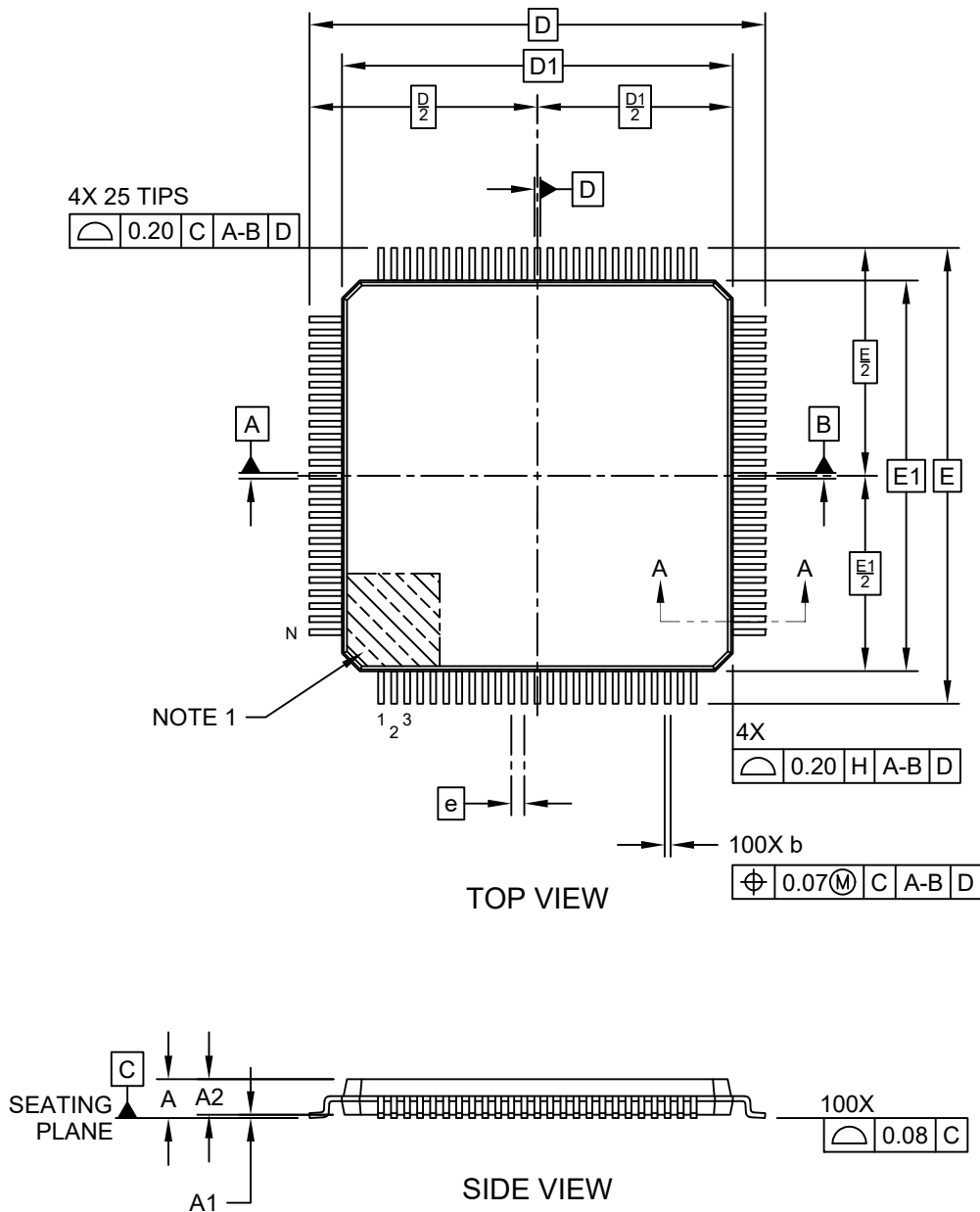
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Contact Pad to Contact Pad (X96)	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

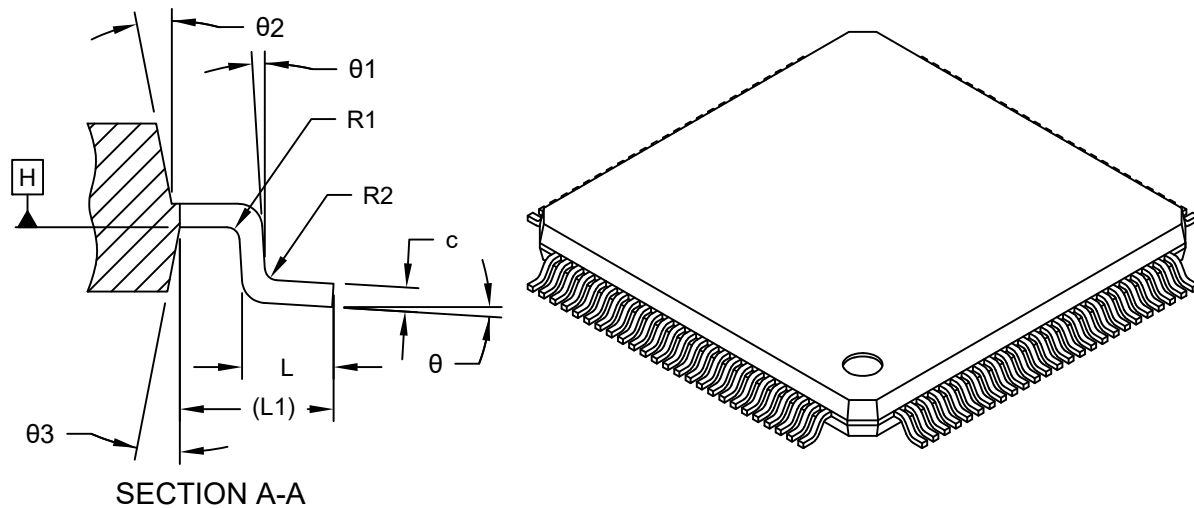
100-Lead Plastic Thin Quad Flatpack (V7X) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



100-Lead Plastic Thin Quad Flatpack (V7X) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



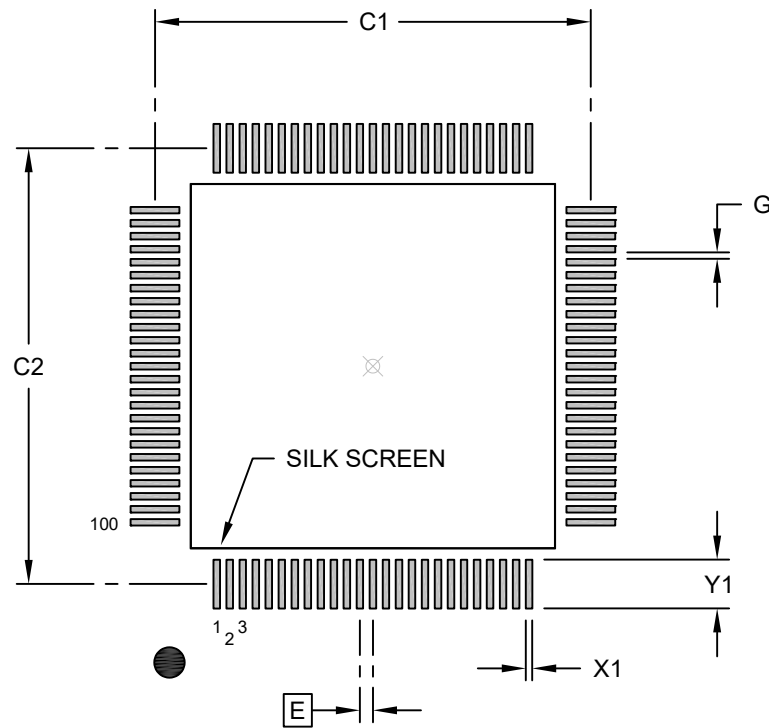
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Standoff	A1	0.05	–	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Length	D	14.00 BSC		
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Overall Width	E	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Lead Width	b	0.13	0.18	0.23
Lead Thickness	c	0.09	–	0.20
Lead Bend Radius	R1	0.08	–	–
Lead Bend Radius	R2	0.08	–	0.20
Foot Angle	θ	0°	–	7°
Lead Angle	θ_1	0°	–	–
Mold Draft Angle	θ_2	11°	12°	13°
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RECOMMENDED LAND PATTERN

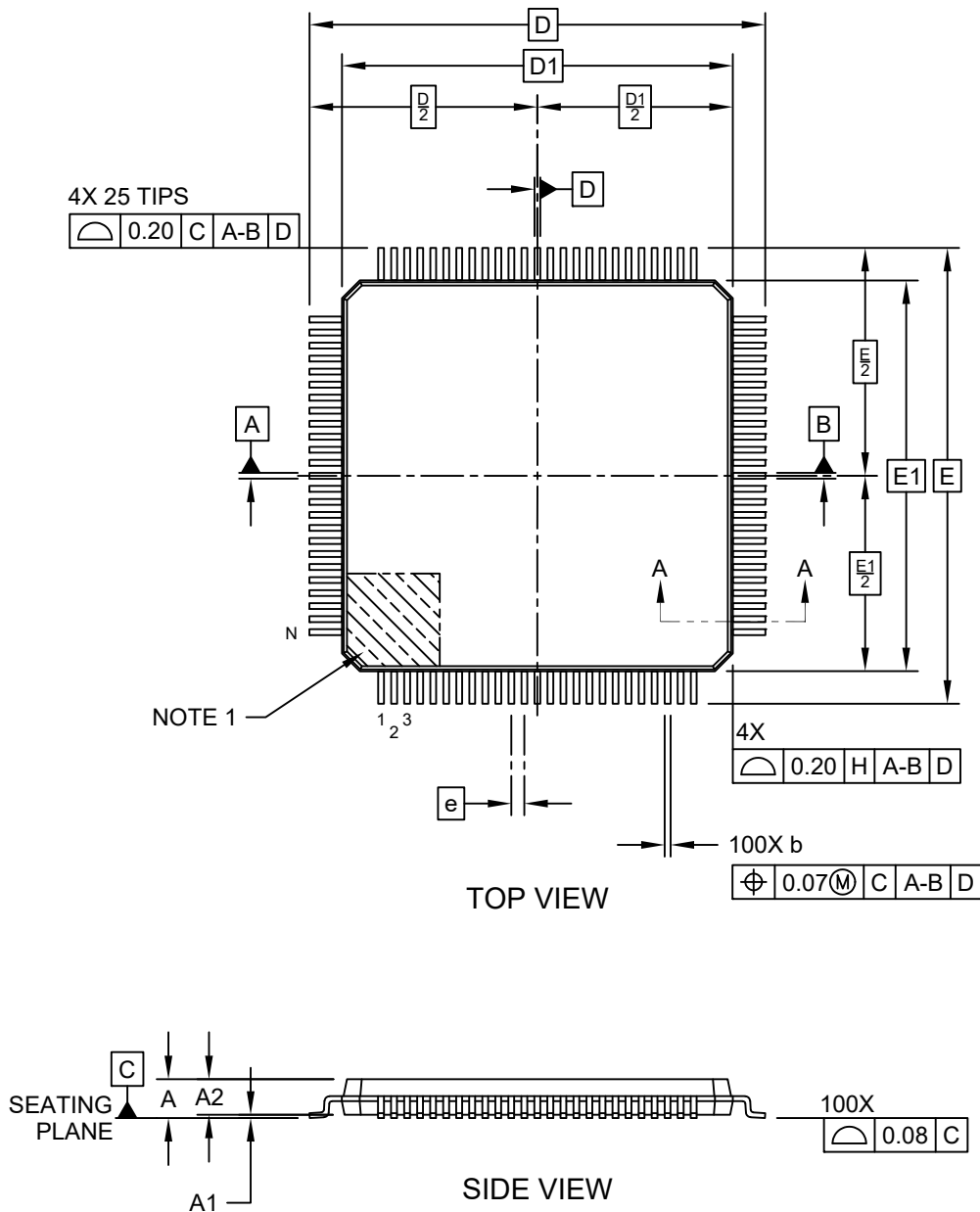
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Contact Pad to Contact Pad (X96)	G	0.20		

Notes:

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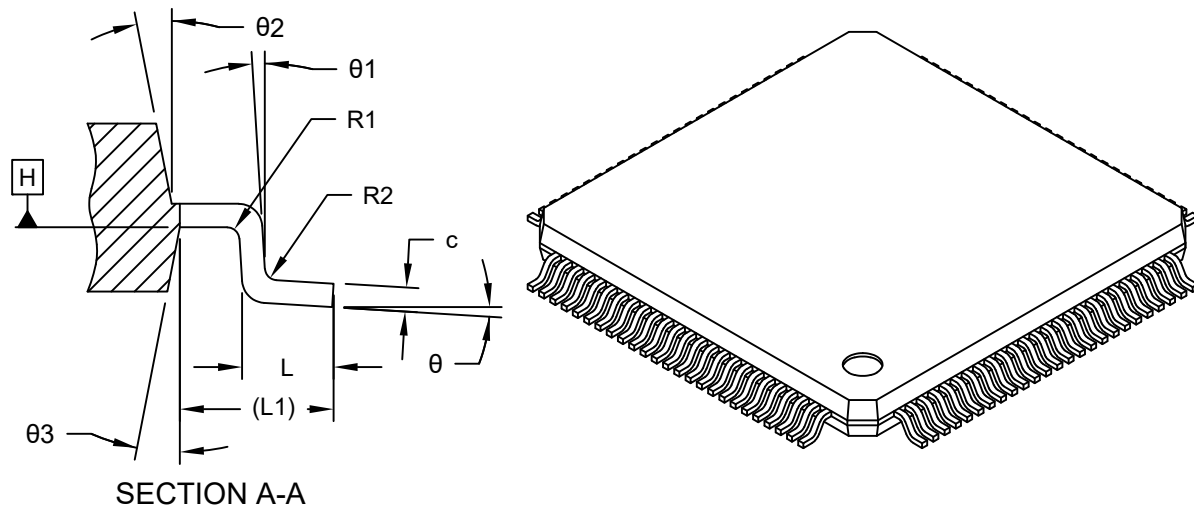
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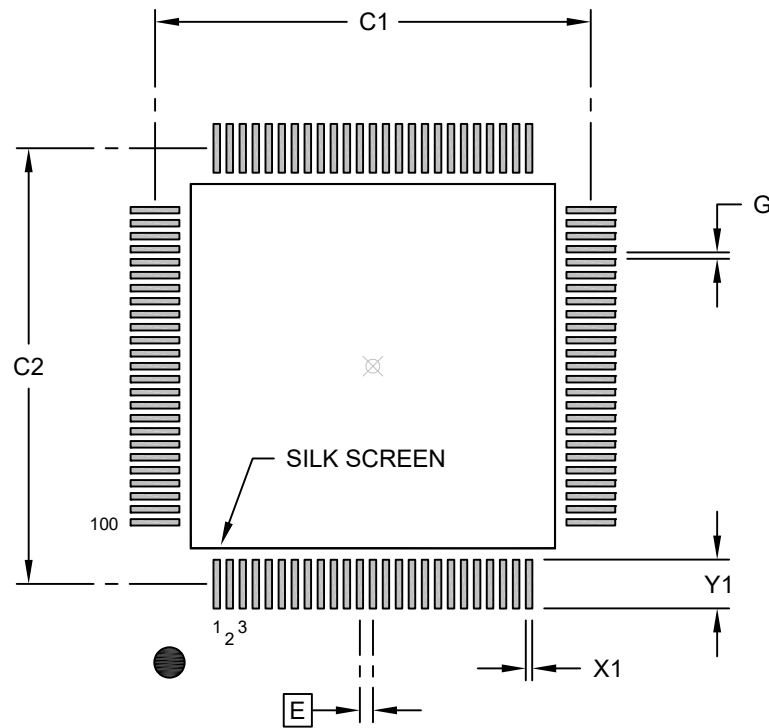
Dimension Limits	Units	MILLIMETERS		
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RECOMMENDED LAND PATTERN

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		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Contact Pad to Contact Pad (X96)	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
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